METHOD FOR PRODUCING BONDED OBJECT AND SEMICONDUCTOR DEVICE AND COPPER BONDING PASTE

[ABSTRACT]

An embodiment of the present invention provides a method for producing a bonded object. The method comprises a step for preparing a laminate in which a first member, a copper bonding paste, and a second member are laminated in order and a step for sintering the copper bonding paste under a pressure of 0.1-1 MPa. The copper bonding paste contains metal particles and a dispersion medium, wherein the content of metal particles is at 50 mass% or more with respect to the total mass of the copper bonding paste, and the metal particles contain 95 mass% or more of submicro copper particles with respect to the total mass of the metal particles.

Figure 2.